

following rewritten paragraph:

A2
--Examples of resins containing such a foaming agent for use as the adhesive (B) include room temperature curing resins such as vinyl acetate emulsion, urea, cyanoacrylate, and urethane; thermosetting resins such as phenol and epoxy; photosetting resins such as urethane-acrylate and epoxy-acrylate; and hot melt resins such as ethylene-vinyl ester copolymers. Among them, crosslinkable polymers such as thermosetting resins and/or photosetting resins are preferable. Especially, photosetting resins are suitable.--

A3
Please replace the paragraph and tables starting on page 40, line 23 and continuing to page 41, line 13, with the following:

--Laminates were manufactured according to Example 7 using the substrates and adhesives of the types shown in Table 2. The results of measurement of Example 8 and Comparative Examples 10 to 14 as well as of Example 7 as to their adhesive powers prior to heating, tensile strength of substrate after heating (hereinafter referred to as "tensile strength") and the presence or absence of adhesive adhering to each substrate after heating (hereinafter referred to as "the presence or absence of adhering adhesive) are shown in Table 2.

Table 2.

*13
Contd*

	Example		Comparative example			
	7	8	10	11	12	13
Substrate 1	A-1	A-2	A-1	A-2	A-2	A-2
Adhesive type	B-5	B-6	C-2	C-5	C-6	B-3
Substrate 2	A-1	A-2	A-1	A-2	A-2	A-2
Adhesive power prior to heating (N/mm ²)	1.2	2.3	2.8	2.8	3.3	1.4
Heating condition ¹⁾	(a)	(b)	(a)	(b)	(b)	(b)
Tensile strength (N/mm ²)	0	0	4.8	2.1	2.6	1.4
Presence or absence of adhering adhesive ²⁾	○	○	×	×	×	×

1) (a): allowed to stand in an oven heated to 160°C for five minutes.

(b): allowed to stand in an oven heated to 150°C for five minutes.

2) The case where any adhesive did not adhere to a substrate after the measurement of tensile strength is represented by 0, while the case where an adhesive adhered to a substrate is represented by X.